

IN THE CLAIMS

Claims 16-25 were previously canceled without prejudice as being drawn to a non-elected invention.

Claims 11 and 27 have previously been canceled without prejudice.

Please cancel claims 26 and 28 without prejudice.

Please enter the pending claims as follows:

1. (Previously Presented) A device having Input/Output (I/O) connections comprising:
 - a bond pad;
 - a passivation layer disposed over said bond pad;
 - vias disposed in said passivation layer to uncover said bond pad;
 - a BLM disposed over said vias, said BLM split into two or more segments, said segments in close proximity to each other, said segments separated by a gap, each of said segments connected to two or more of said vias; and
 - a bump disposed directly on said segments and in said vias.
2. (Previously Presented) The device of claim 1 wherein said bump comprises a Lead-Tin (Pb-Sn) solder.

3. (Previously Presented) The device of claim 1 wherein said bump is free of Lead (Pb).
4. (Previously Presented) The device of claim 1 wherein said bump comprises a ternary alloy comprising Tin-Silver-Copper (Sn-Ag-Cu).
5. (Previously Presented) The device of claim 1 wherein said bump comprises an Electrically Conductive Adhesive (ECA).
6. (Original) The device of claim 1 wherein said BLM provides a diffusion barrier to metals.
7. (Original) The device of claim 1 wherein said BLM comprises a lower layer and an upper layer.
8. (Original) The device of claim 7 wherein said lower layer comprises Titanium (Ti) with a thickness of about 200 to 1500 Angstroms.
9. (Original) The device of claim 7 wherein said upper layer comprises Nickel-Vanadium (Ni-V) with a thickness of about 1000 to 8000 Angstroms.

10. (Original) The device of claim 1 wherein said segments comprise a substantially polygonal layout.

11. (Canceled)

12. (Previously Presented) The device of claim 1, wherein said vias are laterally offset from a center of said bump to which they are electrically connected.

13. (Previously Presented) The device of claim 1 wherein said vias comprise a substantially polygonal layout.

14. (Previously Presented) The device of claim 1, further comprising another bond pad, wherein each of said segments is electrically connected to said bond pad and said another bond pad.

15. (Previously Presented) The device of claim 14 wherein said bond pad and said another bond pad are laterally offset from a center of said bump to which they are electrically connected.

16.-28. (Canceled)